

PCN Number:	20190528000.A	PCN Date:	Sept. 9, 2019
Title:	Datasheet for DS250DFx		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.

Rev A is being issued to correct the information provided in the Anticipated Impact on Fit, Form, Function, Quality or Reliability



DS250DF810

SNLS513A – DECEMBER 2015 – REVISED FEBRUARY 2019

Changes from Original (December 2015) to Revision A

Page

- Updated version ID from 0x31 to 0x32 32



DS250DF800

SNLS519A – JANUARY 2016 – REVISED MAY 2019

February 2019

A

Version ID changed from 0x31 to 0x32



DS250DF410

SNLS456C – MARCH 2016 – REVISED FEBRUARY 2019

Changes from Revision B (September 2018) to Revision C

Page

- Changed Updated the version ID from 0x31 to 0x32 32



DS250DF400

SNLS525B – MARCH 2016 – REVISED FEBRUARY 2019

Changes from Revision A (April 2017) to Revision B

Page

- Changed Updated the version ID from 0x31 to 0x32 30



DS250DF210

SNLS561A – FEBRUARY 2017 – REVISED FEBRUARY 2019

Changes from Original (February 2017) to Revision A

Page

- Updated version ID from 0x31 to 0x32 30

Changes from Revision A (September 2017) to Revision B **Page**

- Changed global register table F0 default value (hex) for bits 1 and 0 **29**

Changes from Original (March 2016) to Revision A **Page**

- Changed Thermal Information table **6**

The datasheet number will be changing.

Device Family	Change From:	Change To:
DS250DF810	SNLS513	SNLS513A
DS250DF800	SNLS519	SNLS519A
DS250DF410	SNLS456B	SNLS456C
DS250DF400	SNLS525A	SNLS525B
DS250DF210	SNLS561	SNLS561A
DS250DF200	SNLS526	SNLS526B

The document is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. The version 0x32 has performance improvement on temperature robustness by increasing the bias current to the divider & FIR. It improved performance at higher temperature comparing to 0x31 version.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DS250DF200ABMR	DS250DF210ABMT	DS250DF410ABMR	DS250DF800ABVT
DS250DF200ABMT	DS250DF400ABMR	DS250DF410ABMT	DS250DF810ABVR
DS250DF210ABMR	DS250DF400ABMT	DS250DF800ABVR	DS250DF810ABVT

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